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# ADC1005 10-Bit µP Compatible A/D Converter

Check for Samples: ADC1005

# FEATURES

- Easy interface to all microprocessors
- Differential analog voltage inputs
- Operates ratiometrically or with 5 V<sub>DC</sub> voltage reference or analog span adjusted voltage reference
- 0V to 5V analog input voltage range with single 5V supply
- On-chip clock generator
- TLL/MOS input/output compatible
- 0.3" standard width 20-pin DIP

# DESCRIPTION

#### NOTE: This device is obsolete. This data sheet is provided for information only.

The ADC1005 is a CMOS 10-bit successive approximation A/D converter. The 20-pin ADC1005 outputs 10-bit data in a two-byte format for interface with 8-bit microprocessors.

The ADC1005 has differential inputs to permit rejection of common-mode signals, allow the analog input range to be offset, and also to permit the conversion of signals not referred to ground. In addition, the reference voltage can be adjusted, allowing smaller voltage spans to be measured with 10-bit resolution.

#### Table 1. Key Specifications

	VALUE	UNIT
Resolution	10	bits
Linearity Error	$\pm \frac{1}{2}$ LSB and $\pm 1$	LSB
Conversion Time	50 µs	

# **Connection Diagram**





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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# Absolute Maximum Ratings (1) (2)

<b>U</b>	
Supply Voltage (V <sub>CC</sub> )	6.5V
Logic Control Inputs	-0.3V to +15V
Voltage at Other Inputs and Outputs	–0.3V to V <sub>CC</sub> +0.3V
Input Current Per Pin	±5 mA
Input Current Per Package	±20 mA
Storage Temperature Range	−65°C to +150°C
Package Dissipation at T <sub>A</sub> =25°C	875 mW
Lead Temperature	
(Soldering, 10 seconds)	
Dual-In-Line Package (Ceramic)	300°C
ESD Susceptibility <sup>(3)</sup>	800V

(1) All voltages are measured with respect to ground.

(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.

(3) Human body model, 100 pF discharged through a 1.5 k $\Omega$  resistor.

# Operating Ratings <sup>(1) (2)</sup>

Supply Voltage (V <sub>CC</sub> )	4.5V to 6.0V
Temperature Range	T <sub>MN</sub> ≤T <sub>A</sub> ≤T <sub>MAX</sub>
ADC1005BCJ, ADC1005BCJ-1,	
ADC1005CCJ-1	−40°C≤T <sub>A</sub> ≤+85°C

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.

(2) All voltages are measured with respect to ground.



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#### **Electrical Characteristics**

The following specifications apply for  $V_{CC} = 5V$ ,  $V_{REF} = 5V$ ,  $f_{CLK} = 1.8$  MHz unless otherwise specified. Boldface limits apply from  $T_{MIN}$  to  $T_{MAX}$ ; All other limits  $T_A = T_j = 25^{\circ}C$ .

Parameter		$\frac{1}{1}$	ADC1005BCJ			ADC1005BCJ-1, ADC1005CCJ-1			Limit
		Conditions	<b>Typ</b> (1)	Tested Limit (2)	Design Limit (3)	Тур (1)	Tested Limit (2)	Design Limit (3)	Unit
Converter Characteris	stics			·			-j	- <u>i</u>	•
Linearity Error (4)									
ADC1005BCJ				±0.5					LSB
ADC1005BCJ-1							±0.5	±0.5	LSB
ADC1005CCJ-1							±1	±1	LSB
Zero Error									
ADC1005BCJ				±0.5					LSB
ADC1005BCJ-1							±0.5	±0.5	LSB
ADC1005CCJ-1							±1	±1	LSB
Fullscale Error									
ADC1005BCJ				±0.5					LSB
ADC1005BCJ-1							±0.5	±0.5	LSB
ADC1005CCJ-1							±1	±1	LSB
Reference	MIN		4.8	2.2		4.8	2.4	2.2	kΩ
Input	MAX		4.8	8.3		4.8	7.6	8.3	kΩ
Resistance									
Common-Mode	MIN			V <sub>CC</sub> +0.05			V <sub>CC</sub> +0.05	V <sub>CC</sub> +0.05	V
Input <sup>(5)</sup>	MAX	V <sub>IN</sub> (+) or V <sub>IN</sub> (−)		GND-0.05			GND-0.05	GND-0.05	V
DC Common-Mode Err	or	Over Common- Mode	±1/8	±1⁄4		±1⁄8	±¼	±¼	LSB
		Input Range							
Power Supply Sensitivi	ty	$V_{CC}=5 V_{DC}\pm 5\%$	±1/8	±1⁄4		±1⁄8	±¼	±1/4	LSB
		$V_{REF} = 4.75 V$							
DC Characteristics									
V <sub>IN(1)</sub> Logical "1" Input		V <sub>CC</sub> =5.25V		2.0			2.0	2.0	V
Voltage	MIN	(except CLK <sub>IN</sub> )							
V <sub>IN(0)</sub> , Logical "0" Input		V <sub>CC</sub> =4.75V		0.8			0.8	0.8	V
Voltage	MAX	(Except CLK <sub>IN</sub> )							
I <sub>IN</sub> , Logical "1" Input		V <sub>IN</sub> =5.0V	0.005	1		0.005	1	1	μA
Current	MAX								
I <sub>IN</sub> , Logical "0" Input		V <sub>IN</sub> =0V	-0.005	-1		-0.005	-1	-1	μA
Current	MAX								
V <sub>T+(MIN)</sub> , Minimum CLK	IN								

Typicals are at 25°C and represent most likely parametric norm. (1)

Tested and guaranteed to National's AOQL (Average Outgoing Quality Level). (2)

Guaranteed, but not 100% production tested. These limits are not used to calculate outgoing quality levels. (3)

Linearity error is defined as the deviation of the analog value, expressed in LSBs, from the straight line which passes through the end (4)

points of the transfer characteristic. For  $V_{IN(-)} \ge V_{IN(+)}$  the digital output code will be 00 0000 0000. Two on-chip diodes are tied to each analog input which will forward conduct for analog input voltages one diode drop below ground or one diode drop greater than  $V_{CC}$  supply. Be careful, during testing at low  $V_{CC}$  levels (4.5V), as high level analog inputs (5V) can cause this input diode to conduct, especially at elevated temperatures, and (5) cause errors for analog inputs near full-scale. The spec allows 50 mV forward bias of either diode. This means that as long as the analog V<sub>IN</sub> does not exceed the supply voltage by more than 50 mV, the output code will be correct. To achieve an absolute 0 V<sub>DC</sub> to 5 V<sub>DC</sub> input voltage range will therefore require a minimum supply voltage of 4.950 V<sub>DC</sub> over temperature variations, initial tolerance and loading.

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# **Electrical Characteristics (continued)**

The following specifications apply for  $V_{CC} = 5V$ ,  $V_{REF} = 5V$ ,  $f_{CLK} = 1.8$  MHz unless otherwise specified. Boldface limits apply from  $T_{MIN}$  to  $T_{MAX}$ ; All other limits  $T_A = T_j = 25^{\circ}C$ .

Parameter			ADC1005BCJ				Limit		
		Conditions	<b>Typ</b> (1)	Tested Limit (2)	Design Limit (3)	<b>Тур</b> (1)	Tested Limit (2)	Design Limit (3)	Unit
Positive going Threshold Voltage			3.1	2.7		3.1	2.7	2.7	V
V <sub>T(MAX)</sub> , Maximum CLK <sub>IN</sub> Positive going Threshold Voltage			3.1	3.5		3.1	3.5	3.5	V
V <sub>T-(MIN)</sub> , Minimum CLK <sub>IN</sub> Negative going Threshold Voltage			1.8	1.5		1.8	1.5	1.5	v
V <sub>T-(MAX)</sub> , Maximum CLK <sub>IN</sub> Negative going Threshold Voltage			1.8	2.1		1.8	2.1	2.1	v
V <sub>H(MIN)</sub> , Minimum CLK <sub>IN</sub> Hysteresis (V <sub>T+</sub> -V <sub>T</sub> -)			1.3	0.6		1.3	0.6	0.6	V
V <sub>H(MAX)</sub> , Maximum CLK <sub>IN</sub> Hysteresis (V <sub>T+</sub> -V <sub>T</sub> -)	I		1.3	2.0		1.3	2.0	2.0	V
V <sub>OUT(1)</sub> , Logical "1" Output Voltage	ЛIN	V <sub>CC</sub> =4.75V I <sub>OUT</sub> =−360 µA I <sub>OUT</sub> =−10 µA		2.4 4.5			2.8 4.6	2.4 4.5	V V
V <sub>OUT(0)</sub> , Logical "0" Output Voltage		V <sub>CC</sub> =4.75V I <sub>OUT</sub> =1.6 mA		0.4			0.34	0.4	V
I <sub>OUT</sub> , TRI-STATE <sup>®</sup> Outpu Current N	t	V <sub>OUT</sub> = 0V V <sub>OUT</sub> = 5V	-0.01 0.01	-3 3		-0.01 0.01	-0.3 0.3	-3 3	μΑ μΑ
I <sub>SOURCE</sub> , Output Source Current MIN		V <sub>OUT</sub> =0V	-14	-6.5		-14	-7.5	-6.5	mA
I <sub>SINK</sub> , Output Sink Current N	ЛIN	V <sub>OUT</sub> =5V	16	8.0		16	9.0	8.0	mA
I <sub>CC</sub> , Supply Current N		f <sub>CLK</sub> =1.8 MHz <del>CS</del> ="1"	1.5	3		1.5	2.5	3	mA



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#### **AC Electrical Characteristics**

The following specifications apply for  $V_{CC} = 5V$ ,  $V_{REF} = 5V$ ,  $V_{rEF} = 5V$ ,  $t_r = t_f = 20$  ns unless otherwise specified. Boldface limits apply from  $T_{MIN}$  to  $T_{MAX}$ ; All other limits  $T_A = T_j = 25^{\circ}C$ .

			Тур	Tested	Design	Limit	
Parameter		Conditions	(1)	Limit	Limit	Units	
				(2)	(3)		
f <sub>CLK</sub> , Clock Frequency	MIN			0.2	0.2	MHz	
	MAX			2.6	2.6	MHz	
Clock Duty Cycle	MIN			40	40	%	
	MAX			60	60	%	
t <sub>C</sub> , Conversion Time	MIN			80	80	1/f <sub>CLK</sub>	
	MAX			90	90	1/f <sub>CLK</sub>	
	MIN	f <sub>CLK</sub> =1.8 MHz		45	45	μs	
	MAX	f <sub>CLK</sub> =1.8 MHz		50	50	μs	
$t_{W(\overline{WR})L}$ , Minimum $\overline{WR}$ Pulse Width		<u>CS</u> =0	100	150	150	ns	
ACC, Access Time (Dela		CS =0	170	300	300	ns	
falling edge of RD to Out Valid)	tput Data	$C_L$ =100 pF, $R_L$ = 2k					
t <sub>1H</sub> , t <sub>0H</sub> , TRI-STATE Con	trol	R <sub>L</sub> =10k, C <sub>L</sub> =10 pF	125		200	ns	
(Delay from Rising Edge of RD to Hi-Z State)		R <sub>L</sub> =2k, C <sub>L</sub> =100 pF	145	230	230	ns	
$t_{WI,} t_{RI}$ , Delay from Falling Edge of WR or RD to Reset of INTR			300	450	450	ns	
t <sub>IRS</sub> , <mark>INTR</mark> to 1st Read Set-up Time			400	550	550	ns	
CIN, Capacitance of Logic Inputs			5		7.5	pF	
C <sub>OUT</sub> , Capacitance of Lo Outputs	gic		5		7.5	pF	

(1) Typicals are at 25°C and represent most likely parametric norm.

(2)

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#### **Functional Diagram**





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**TEST CIRCUIT DIAGRAMS** 

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## **Timing Diagrams**



Figure 3. Output Enable and Reset INTR



Note: All timing is measured from the 50% voltage points.

Table 2.	Byte	Sequencing	for	ADC1005
----------	------	------------	-----	---------

Byte	8-Bit Data Bus Connection									
Order	DB7	DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0								
	MSB									
1st	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2		
		LSB								
2nd	Bit 1	Bit 0	0	0	0	0	0	0		



## **Block Diagram**



#### **Functional Description**

#### GENERAL OPERATION

A block diagram of the A/D converter is shown in Block Diagram. All of the inputs and outputs are shown and the major logic control paths are drawn in heavier weight lines.

#### **Converter Operation**

The ADC1005 uses an advanced potentiometric resistive ladder network. The analog inputs, as well as the taps of this ladder network are switched into a weighted capacitor array. The output of this capacitor array is the input to a sampled data comparator. This comparator allows the successive approximation logic to match the analog input voltage  $[V_{IN}(+) - V_{IN}(-)]$  to taps on the R network. The most significant bit is tested first and after 10 comparisons (80 clock cycles) a digital 10-bit binary code (all "1"s = full-scale) is transferred to an output latch.



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#### Starting a Conversion

The conversion is initialized by taking  $\overline{CS}$  and  $\overline{WR}$  simultaneously low. This sets the start flip-flop (F/F) and the resulting "1" level resets the 10-bit shift register, resets the interrupt (INTR) F/F and inputs a "1" to the D flop, F/F1, which is at the input end of the 10-bit shift register. Internal clock signals then transfer this "1" to the Q output of F/F1. The AND gate, G1, combines this "1" output with a clock signal to provide a reset signal to the start F/F. If the set signal is no longer present (either WR or  $\overline{CS}$  is a "1") the start F/F is reset and the 10-bit shift register then can have the "1" clocked in, allowing the conversion process to continue. If the set signal were still present, this reset pulse would have no effect and the 10-bit shift register would continue to be held in the reset mode. This logic therefore allows for wide  $\overline{CS}$  and  $\overline{WR}$  signals. The converter will start after at least one of these signals returns high and the internal clocks again provide a reset signal for the start F/F.

To summarize, on the high-to-low transition of the  $\overline{WR}$  input the internal SAR latches and the shift register stages are reset. As long as the  $\overline{CS}$  input and  $\overline{WR}$  input remain low, the A/D will remain in a reset state. *Conversion will start after at least one of these inputs makes a low-to-high transition.* 

#### **Output Control**

After the "1" is clocked through the 10-bit shift register (which completes the SAR search) it causes the new digital word to transfer to the TRI-STATE output latches. When the XFER signal makes a high-to-low transition the one shot fires, setting the INTR F/F. An inverting buffer then supplies the INTR output signal.

Note that this SET control of the INTR F/F remains low for approximately 400 ns. If the data output is continuously enabled (CS and RD both held low) the INTR output will still signal the end of the conversion (by a high-to-low transition). This is because the SET input can control the Q output of the INTR F/F even though the RESET input is constantly at a "1" level. This INTR output will therefore stay low for the duration of the SET signal.

When data is to be read, the combination of both  $\overline{CS}$  and  $\overline{RD}$  being low will cause the INTR F/F to be reset and the TRI-STATE output latches will be enabled.

#### Free-Running and Self-Clocking Modes

For operation in the free-running mode an initializing pulse should be used, following power-up, to ensure circuit operation. In this application, the CS input is grounded and the WR input is tied to the INTR output. This WR and INTR node should be momentarily forced to logic low following a power-up cycle to ensure start up.

The clock for the A/D can be derived from the CPU clock or an external RC can be added to provide selfclocking. The CLK IN makes use of a Schmitt trigger as shown in Figure 4.



 $f_{CLK} \cong \frac{1}{1.1 \text{ RC}}$ 

Figure 4. Self-Clocking the A/D

#### **REFERENCE VOLTAGE**

The voltage applied to the reference input of these converters defines the voltage span of the analog input (the difference between  $V_{IN(MAX)}$  and  $V_{IN(MIN)}$ ) over which the 1024 possible output codes apply. The devices can be used in either ratiometric applications or in systems requiring absolute accuracy. The reference pin must be connected to a voltage source capable of driving the reference input resistance of typically 4.8 k $\Omega$ . This pin is the top of a resistor divider string used for the successive approximation conversion.



In a ratiometric system (Figure 5) the analog input voltage is proportional to the voltage used for the A/D reference. This voltage is typically the system power supply, so the  $V_{REF}$  pin can be tied to  $V_{CC}$ . This technique relaxes the stability requirements of the system references as the analog input and A/D reference move together maintaining the same output code for a given input condition.

For absolute accuracy (Figure 6), where the analog input varies between very specific voltage limits, the reference pin can be biased with a time and temperature stable voltage source. The LM385 and LM336 reference diodes are good low current devices to use with these converters.

The maximum value of the reference is limited to the  $V_{CC}$  supply voltage. The minimum value, however, can be small to allow direct conversions of transducer outputs providing less than a 5V output span. Particular care must be taken with regard to noise pickup, circuit layout, and system error voltage sources when operating with a reduced span due to the increased sensitivity of the converter (1 LSB equals  $V_{REF}/1024$ ).



Figure 5. Ratiometric



Figure 6. Absolute with a Reduced Span

#### THE ANALOG INPUTS

# Analog Differential Voltage Inputs and Common-Mode Rejection

The differential inputs of these converters reduce the effects of common-mode input noise, which is defined as noise common to both selected "+" and "-" inputs (60 Hz is most typical). The time interval between sampling the "+" input and the "-" input is half of an internal clock period. The change in the common-mode voltage during this short time interval can cause conversion errors. For a sinusoidal common-mode signal, this error is:

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(1)

$$V_{\text{ERROR(MAX)}} = V_{\text{PEAK}} (2\pi \text{ f}_{\text{CM}}) imes rac{4}{\text{f}_{\text{CLK}}}$$

where  $f_{CM}$  is the frequency of the common-mode signal,  $V_{PEAK}$  is its peak voltage value and  $f_{CLK}$  is the clock frequency at the CLK IN pin.

For a 60 Hz common-mode signal to generate a ¼ LSB error (1.2 mV) with the converter running at 1.8 MHz, its peak value would have to be 1.46V. A common-mode signal this large is much greater than that generally found in data acquisition systems.

# Input Current

Due to the sampling nature of the analog inputs, short duration spikes of current enter the "+" input and exit the "-" input at the clock rising edges during the conversion. These currents decay rapidly and do not cause errors as the internal comparator is strobed at the end of a clock period.

## Input Bypass Capacitors

Bypass capacitors at the inputs will average the current spikes noted in 3.2 and cause a DC current to flow through the output resistances of the analog signal sources. This charge pumping action is worse for continuous conversions with the  $V_{IN}(+)$  input voltage at full scale. For continuous conversions with a 1.8 MHz clock frequency with the  $V_{IN}(+)$  input at 5V, this DC current is at a maximum of approximately 5  $\mu$ A. Therefore, *bypass capacitors should not be used at the analog inputs or the*  $V_{REF}$  *pin* for high resistance sources (>1 k $\Omega$ ). If input bypass capacitors are necessary for noise filtering and high source resistance is desirable to minimize capacitor size, the detrimental effects of the voltage drop across this input resistance, which is due to the average value of the input current, can be eliminated with a full-scale adjustment while the given source resistor and input bypass capacitor are both in place. This is possible because the average value of the input current is a linear function of the differential input voltage.

## Input Source Resistance

Large values of source resistance where an input bypass capacitor is not used, *will not cause errors* if the input currents settle out prior to the comparison time. If a low pass filter is required in the system, use a low valued series resistor ( $\leq 1 \text{ k}\Omega$ ) for a passive RC section or add an op amp RC active low pass filter. For low source resistance applications ( $\leq 0.1 \text{ k}\Omega$ ) a 4700 pF bypass capacitor at the inputs will prevent pickup due to series lead induction of a long wire. A 100 $\Omega$  series resistor can be used to isolate this capacitor – both the R and the C are placed outside the feedback loop – from the output of an op amp, if used.

#### Noise

The leads to the analog inputs (pins 6 and 7) should be kept as short as possible to minimize input noise coupling. Both noise and undesired digital clock coupling to these inputs can cause system errors. The source resistance for these inputs should, in general, be kept below 1 k $\Omega$ . Larger values of source resistance can cause undesired system noise pickup. Input bypass capacitors, placed from the analog inputs to ground, can reduce system noise pickup but can create analog scale errors. See Input Current, Input Bypass Capacitors, and Input Source Resistance if input filtering is to be used.

#### OFFSET AND REFERENCE ADJUSTMENT

# Zero Offset

The zero error of the A/D converter relates to the location of the first riser of the transfer function and can be measured by grounding the V(-) input and applying a small magnitude positive voltage to the V(+) input. Zero error is the difference between the actual DC input voltage that is necessary to just cause an output digital code transition from 00 0000 0000 to 00 0000 0001 and the ideal ½ LSB value (½ LSB = 2.45 mV for V<sub>REF</sub> = 5.0 V<sub>DC</sub>).

The zero of the A/D normally does not require adjustment. However, for cases where  $V_{IN(MIN)}$  is not ground and in reduced span applications ( $V_{REF} < 5V$ ), an offset adjustment may be desired. The converter can be made to output an all zero digital code for an arbitrary input by biasing the A/D's  $V_{IN}(-)$  input at that voltage. This utilizes the differential input operation of the A/D.



# www.ti.com Full Scale

The full-scale adjustment can be made by applying a differential input voltage that is  $1\frac{1}{2}$  LSB down from the desired analog full-scale voltage range and then adjusting the magnitude of the V<sub>REF</sub> input for a digital output code that is just changing from 11 1111 1110 to 11 1111 1111.

#### Adjusting for an Arbitrary Analog Input Voltage Range

If the analog zero voltage of the A/D is shifted away from ground (for example, to accommodate an analog input signal that does not go to ground), this new zero reference should be properly adjusted first. A  $V_{IN}(+)$  voltage that equals this desired zero reference plus ½ LSB (where the LSB is calculated for the desired analog span, 1 LSB = analog span/1024) is applied to selected "+" input and the zero reference voltage at the corresponding "-" input should then be adjusted to just obtain the  $000_{HEX}$   $001_{HEX}$  code transition.

The full-scale adjustment should be made [with the proper  $V_{IN}(-)$  voltage applied] by forcing a voltage to the  $V_{IN}(+)$  input given by:

$$V_{\text{IN}}(+) \text{ FS adj} = V_{\text{MAX}} - 1.5 \left[ \frac{(V_{\text{MAX}} - V_{\text{MIN}})}{1024} \right]$$

(2)

where  $V_{MAX}$  = the high end of the analog input range and  $V_{MIN}$  = the low end (the offset zero) of the analog range. (Both are ground referenced).

The  $V_{REF}$  (or  $V_{CC}$ ) voltage is then adjusted to provide a code change from  $3FF_{HEX}$  to  $3FE_{HEX}$ . This completes the adjustment procedure.

For an example see the Zero-Shift and Span-Adjust circuit below.

#### POWER SUPPLIES

Noise spikes on the V<sub>CC</sub> supply line can cause conversion errors as the comparator will respond to this noise. A low inductance tantalum filter capacitor should be used close to the converter V<sub>CC</sub> pin and values of 1  $\mu$ F or greater are recommended. If an unregulated voltage is available in the system, a separate LM340LAZ-5.0, TO-92, 5V voltage regulator for the converter (and the other analog circuitry) will greatly reduce digital noise on the V<sub>CC</sub> supply.

A single point analog ground that is separate from the logic ground points should be used. The power supply bypass capacitor and the self-clocking capacitor (if used) should both be returned to the digital ground. Any  $V_{REF}$  bypass capacitors, analog input filters capacitors, or input signal shielding should be returned to the analog ground point.



Figure 7. Zero-Shift and Span-Adjust ( $2V \le V_{IN} \le 5V$ )

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## **Typical Applications**















# **TRI-STATE Test Circuits and Waveforms**







t<sub>r</sub>=20 ns





Figure 13.  $t_{IH}$ , C<sub>L</sub>=10 pF



t<sub>r</sub>=20 ns

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